

MANUFACTURER DOCUMENT PACKAGE

Manufacturer's Manual

Reference package for procurement and maintenance review

TRICONEX

7400063-100

TRICON MAIN PROCESSOR MODULE

Used with the applicable Triconex safety system configuration.

REFERENCE PACKAGE

OFFICIAL DOCUMENT

Selected official manufacturer pages follow this cover.

Source: Tricon Technical Product Guide

Main Processor Modules

Model 3008 Main Processors (MP) are available for Tricon v9.6 and later systems. For detailed specifications, see the *Planning and Installation Guide for Tricon Systems*.

Three MPs must be installed in the Main Chassis of every Tricon system. Each MP independently communicates with its I/O subsystem and executes the user-written control program.

Sequence of Events (SOE) and Time Synchronization

During each scan, the MPs inspect designated discrete variables for state changes known as *events*. When an event occurs, the MPs save the current variable state and time stamp in the buffer of an SOE block.

If multiple Tricon systems are connected by means of NCMs, the time synchronization capability ensures a consistent time base for effective SOE time-stamping. See page 78 for more information.

Diagnostics

Extensive diagnostics validate the health of each MP, I/O module and communication channel. Transient faults are recorded and masked by the hardware majority-voting circuit. Persistent faults are diagnosed and the errant module is hot-replaced.

MP diagnostics perform these tasks:

- Verify fixed-program memory and static RAM

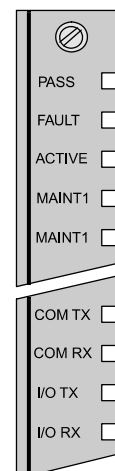
- Test all basic processor and floating-point instructions and operating modes
- Validate user memory by means of the TriBus hardware-voting circuitry
- Verify the shared memory interface with each I/O communication processor and channel
- Verify handshake and interrupt signals between the CPU, each I/O communication processor and channel
- Check each I/O communication processor and channel microprocessor, ROM, shared memory access and loopback of RS-485 transceivers
- Verify the TriClock and TriBus interfaces

Physical Description of Model 3008 Main Processors

Feature	Description
Microprocessor	Motorola MPC860, 32 bit, 50 MHz
Memory	• 16 MB DRAM (non-battery backed-up) • 32 KB SRAM, battery backed-up • 6 MB Flash PROM
TriBus Communication Rate	• 25 megabits per second • 32-bit CRC protected • 32-bit DMA, fully isolated
I/O Bus and Communication Bus Processors	• Motorola MPC860 • 32 bit • 50 MHz

Indicators on Main Processors

PASS	Module has passed self-diagnostic tests
FAULT	Module has a fault and should be replaced
ACTIVE	Module is executing the user-written control program
MAINT1	Maintenance indicator 1
MAINT2	Maintenance indicator 2
COM TX	Transmitting data across COMM bus
COM RX	Receiving data from COMM bus
I/O TX	Transmitting data across I/O bus
I/O RX	Receiving data from I/O bus



Tricon Communication Module

The Tricon Communication Module (TCM), which is compatible with only Tricon v10.0 and later systems, allows the Tricon controller to communicate with the TriStation 1131 software, other Tricon, Trident™, or Tri-GP controllers, Modbus master and slave devices, and external hosts over Ethernet networks.

Each TCM contains four serial ports, two network ports, and one debug port (for Invensys use).

Each serial port is uniquely addressed and can be configured as a Modbus master or slave. Serial Port #1 supports either the Modbus or the Trimble GPS interface. Serial Port #4 supports either the Modbus or the TriStation interface. Each TCM supports an aggregate data rate of 460.8 kilobits per second, for all four serial ports.

Any standard Modbus device can communicate with the Tricon controller through the TCM, provided that aliases are assigned to the Tricon variables.

Chassis Options

A Tricon system is made up of one or more chassis assemblies which contain I/O and communication modules. The first chassis of a system is called the Main Chassis (Model 8110). To enlarge a system, Expansion Chassis (Model 8111 or 8121) and/or RXM Chassis (Model 8112) can be added. (See “System Configuration” on page 11 for details.)

I/O Expansion Bus

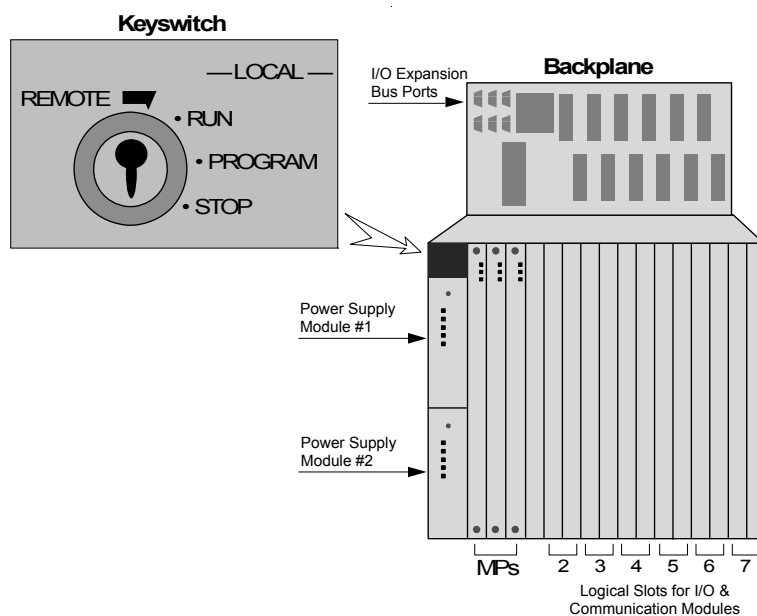
Each chassis has six RS-485 I/O expansion bus ports at the top left corner of the backplane. There are two sets of ports for channels A, B, and C, providing for two triplicated serial communications paths between chassis. One set of cables is required for each Expansion Chassis and for the RXM Chassis which houses the primary RXM Module set. The standard length of a cable set (Model 9000) is 6 feet—longer cables are available if needed.

The triplicated I/O bus transfers data between the I/O modules and the Main Processors at 375 kilobits per second. The communication bus runs between the Main Processors and the communication modules at 2 megabits per second.

Mechanical Specifications

These specifications apply to Main, Expansion, and RXM Chassis; Power Supply Modules; and other modules where indicated.

Overall Dimensions	19 in wide by 22.75 in high by 17.75 in deep (48.3 cm by 57.8 cm by 45.1 cm)
Chassis Fabrication	Black zinc-plated and welded cold-rolled steel
Approximate Weights	
Main or Expansion Chassis	54.0 lbs. (24.5 kg.)
Power Module	7.2 lbs. (3.3 kg.)
Main Processor	4.7 lbs. (2.1 kg.)
I/O Module	4.7 to 6.0 lbs. (2.1 kg. to 2.7 kg.)
HART Interface Module	4.8 lbs. (2.2 kg.)
Communication Module	5.0 lbs. (2.3 kg.)
16-point Termination Panel	.09 lbs. (.04 kg.)
32-point Termination Panel	2.1 lbs. (.95 kg.)



Keyswitch for System Control

The Main Chassis has a four-position keyswitch which controls all the chassis in the system. The keyswitch setting is readable by Tricon controllers, TriStation 1131 software, and the control programs. Switch settings are:

RUN—Normal operation with read-only capability. The Main Processors execute the previously-loaded control

program. Attempts to modify program variables by a TriStation 1131 application, Modbus masters, or external hosts are rejected. However, a control program may call gated access functions to enable external host writes during a designated window of time.

PROGRAM—For program loading and checkout. Allows control of the Tricon system from the TriStation 1131 platform, including Download All and Download Changes. Also allows writes to program variables by external hosts.

STOP—Stops reading inputs, forces non-retentive digital and analog outputs to 0, and halts the control program. (Retentive outputs retain the value they had before the keyswitch was turned to Stop.) The Stop setting can be used for installation and service of process-related equipment, *but is not required for service of the Tricon controller.*

REMOTE—Allows writes to program variables by TriStation 1131 application and external hosts. (Download All and Download Changes by the TriStation 1131 software are not allowed.) Modification of program logic is not allowed.

Product Specifications

Chassis and Mounting Specifications

The Tricon system can be rack-mounted or panel-mounted in an industry-standard NEMA enclosure as described on the next page. Cabinets can optionally be equipped with base and casters. Multiple cabinets can be bolted together on the sides, but sufficient clearance must be allowed to fully open their front and rear doors.

Slot Covers

All unused slots in a chassis should be filled with Blank I/O Slot Panels (Model 8105) to maintain proper air flow.

Heat Management

When mounting Tricon chassis into vented or non-vented enclosures, the

integration engineer must make provisions for sufficient heat management.

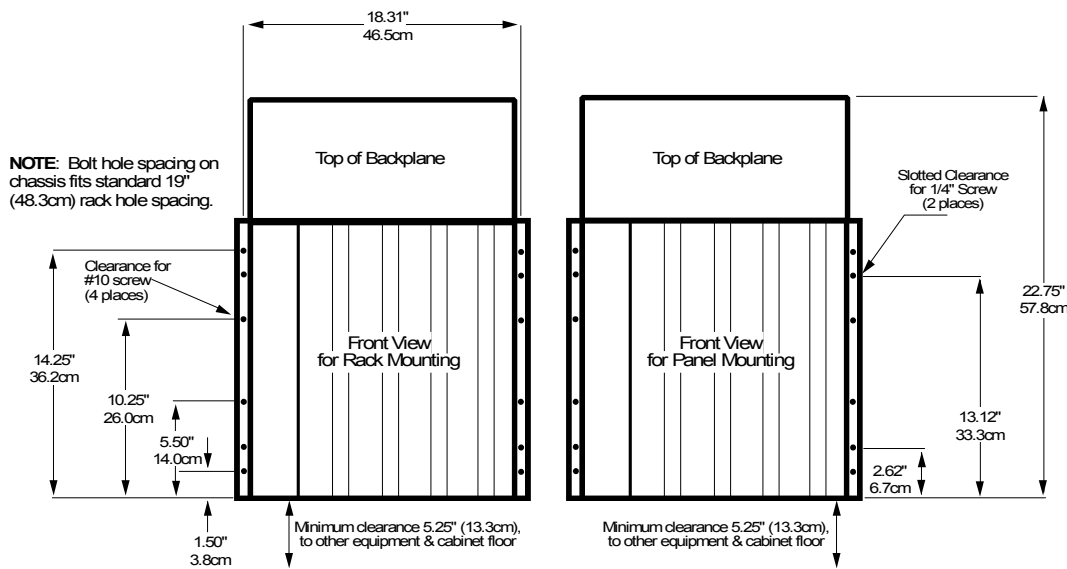
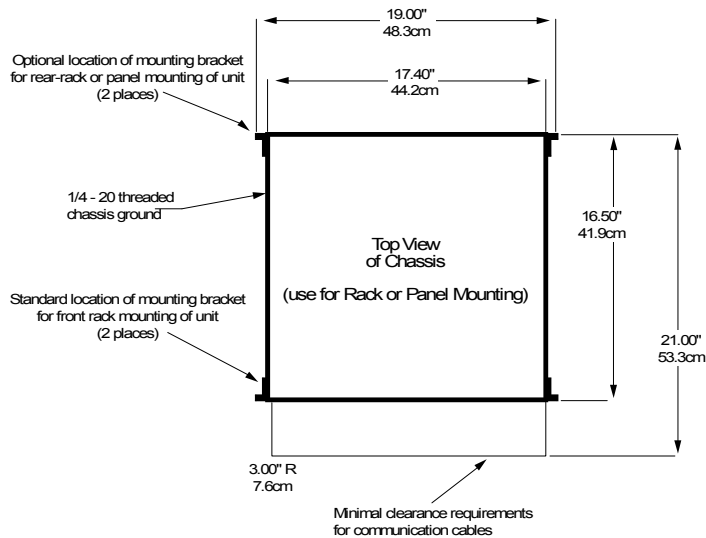
You can manage the temperature of the enclosure by using either convection cooling or fans.

All enclosure installations must meet these two requirements:

- The temperature rise through each chassis must not exceed 27° F (15° C), as measured at the screened area at the top of the chassis at all points.
- The inlet temperature into the screened area at the bottom of each chassis must not exceed 140° F (60° C) at all points.

For temperatures above 86° F, Invensys recommends installing baffles (Triconex part number 2000361-001), as shown on page 25. For higher temperatures, other heat management components should be implemented:

- Louvers and pagoda top
- Lower-density filters
- Redundant fans (running all the time)
- Failure detection circuitry



Dimensions and Clearances for Rack and Panel Mounting